

**AMENDMENTS TO THE CLAIMS**

Please add claims 10 and 11 as set forth below.

1. (CANCELED)
2. (PREVIOUSLY PRESENTED) A camera system having a camera module comprising:
  - a flexible substrate provided with a through-hole for light transmission;
  - an imaging element having a light receiving portion, wherein said imaging element is flip chip mounted on a first side of the substrate such that the light receiving portion is exposed through the through-hole; and
  - a lens unit mounted on a second side of the substrate to cover a space over the light receiving portion of the imaging element.
3. (CANCELED)
4. (PREVIOUSLY PRESENTED) The camera system of claim 2, wherein the imaging element has the light receiving portion on a first side and a shielding layer on a second side opposite to the first side.
5. (PREVIOUSLY PRESENTED) An imaging device comprising:
  - a substrate; and
  - an imaging element having a light receiving portion on a first side, and a shielding layer on a second side that is opposite the first side, wherein said imaging element is flip chip mounted on the substrate such that said first side is opposed to the substrate.
6. (PREVIOUSLY PRESENTED) An imaging device comprising:
  - a substrate having a through-hole for light transmission; and
  - an imaging element having a light receiving portion on a first surface, wherein said imaging element is flip chip mounted on one side of the substrate such that the light receiving portion is exposed through the through-hole; and
  - a shielding layer on a back surface of the imaging element, wherein said back surface is opposite to the first surface of the imaging element having the light receiving portion.

7. (PREVIOUSLY PRESENTED) The imaging device according to Claim 5, wherein a black resin is applied to the periphery of the imaging element including a connecting portion located between the substrate and the imaging element by the flip chip mounting to cover the side surface and the back surface of the imaging element, and wherein a portion of the resin is the shielding layer.

8. (PREVIOUSLY PRESENTED) A camera module comprising:  
a substrate having a through-hole for light transmission;  
an imaging element having a light receiving portion on a first surface of the imaging element and a shielding layer on a back surface of the imaging element, wherein said imaging element is flip chip mounted on a first side of the substrate such that the light receiving portion is exposed through the through-hole, and a lens unit mounted on a second side of the substrate.

9. (PREVIOUSLY PRESENTED) A camera system using a camera module comprising:  
a substrate having a through-hole for light transmission;  
an imaging element having a light receiving portion on a first surface of the imaging element and a shielding layer on a back surface of the imaging element, wherein said imaging element is flip chip mounted on a first side of the substrate such that the light receiving portion is exposed through the through-hole, and a lens unit is mounted on a second side of the substrate.

10. (NEW) An optical system having an optical module, said optical module comprising:  
a flexible substrate provided with a through-hole;  
an optical element having an optical portion that is flip chip mounted on a first side of the flexible substrate such that the optical portion is exposed through the through-hole;  
a lens unit mounted on a second side of the substrate to cover a space over the optical portion of the optical element; and  
a system module connected to the flexible substrate in the optical module, wherein integrated circuits are mounted on the system module.

11. (NEW) The optical system of claim 1, wherein the optical element is a light emitting element.